

Radiation Report

# SN55LVTA4-SEP Single-Event Effects (SEE) Radiation Report

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ABSTRACT

The purpose of this study is to characterize the single-event-effects (SEE) performance due to heavy-ion irradiation of the SN55LVTA4-SEP. SEE performance was verified at minimum (3V) and maximum (3.6V) operating conditions. Heavy-ions with an LET<sub>EFF</sub> of 50MeV-cm<sup>2</sup>/ mg were used to irradiate five production devices with a fluence of 1 × 10<sup>7</sup> ions / cm<sup>2</sup>. The results demonstrate that the SN55LVTA4-SEP is SEL-free up to LET<sub>EFF</sub> = 50MeV-cm<sup>2</sup> / mg as 125°C. SET performance at minimum and maximum operating voltages saw no excursions ≥ |5%|, as shown and discussed in this report.

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## 1 Overview

The SN55LVTA4-SEP is a radiation tolerant quad channel differential line driver that implements the electrical characteristics of low-voltage differential signaling (LVDS) with a 3.3V supply. This driver delivers a minimum differential output voltage magnitude of 247mV into a 100Ω load when enabled.

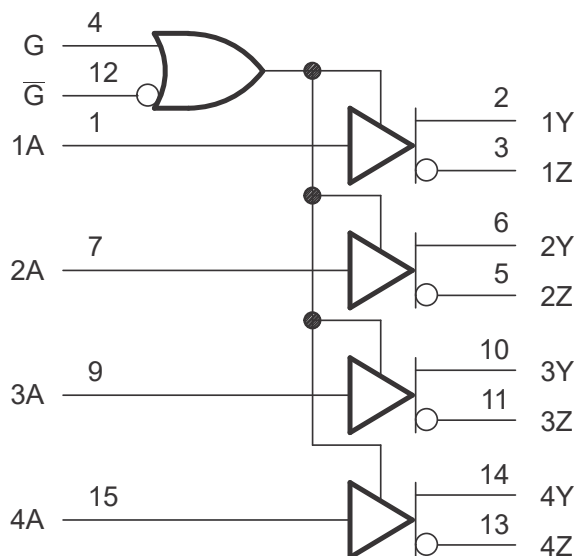
For more information, see the SN55LVTA4-SEP [product page](#).

**Table 1-1. Overview Information**

Description	Device Information
TI Part Number	SN55LVTA4-SEP
Orderable Part Number	SN55LVTA4MDTSEP
VID Number	V62/25605
Device Function	Radiation-tolerant, Quad channel differential line driver
Technology	LIN3B
Exposure Facility	Facility for Rare Isotope Beams (FRIB) at Michigan State University – FRIB Single Event Effects (FSEE) Facility
Heavy Ion Fluence per Run	$1 \times 10^7$ ions / cm <sup>2</sup>
Irradiation Temperature	25°C (for SET testing) and 125°C (for SEL testing)

## 2 Single-Event Effects (SEE)

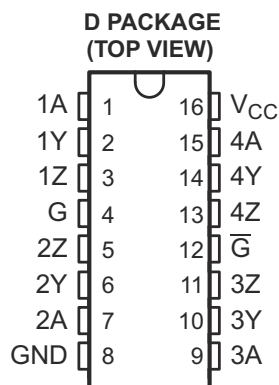
The primary single-event effect (SEE) event of interest in the SN55LVTA4-SEP is the destructive single-event latch-up. From a risk or impact perspective, the occurrence of an SEL is potentially the most destructive SEE event and the biggest concern for space applications. In mixed technologies such as the Linear Bi-CMOS (LIN3B) process used for SN55LVTA4-SEP, the CMOS circuitry introduces a potential SEL susceptibility. SEL can occur if excess current injection caused by the passage of an energetic ion is high enough to trigger the formation of a parasitic cross-coupled PNP and NPN bipolar structure (formed between the p-substrate and n-well and n+ and p+ contacts). The parasitic bipolar structure initiated by a single-event creates a high-conductance path (inducing a steady-state current that is typically orders-of-magnitude higher than the normal operating current) between power and ground that persists (is latched) until power is removed or until the device is destroyed by the high-current state. The process modifications applied for SEL-mitigation were sufficient, as the SN55LVTA4-SEP exhibited no SEL with heavy-ions up to an  $LET_{EFF}$  of  $50\text{MeV}\cdot\text{cm}^2 / \text{mg}$  at a fluence of  $1 \times 10^7$  ions /  $\text{cm}^2$  and a chip temperature of  $125^\circ\text{C}$ .



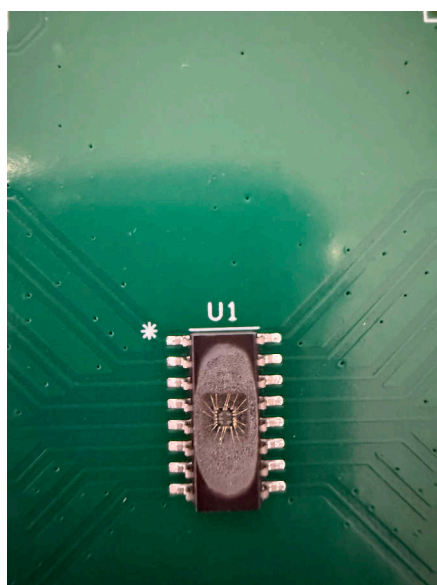
**Figure 2-1. Functional Block Diagram of the SN55LVTA4-SEP**

### 3 Test Device and Test Board Information

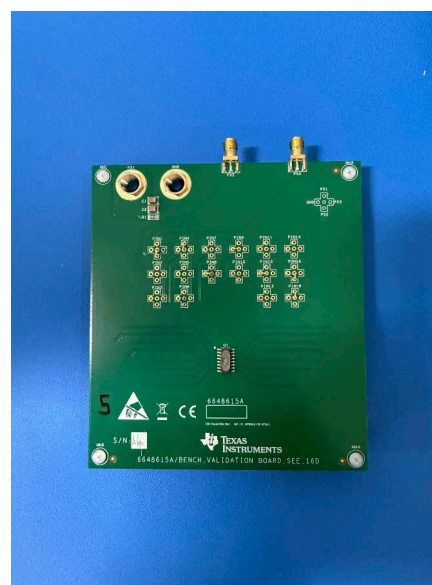
The SN55LVTA4-SEP is a packaged 16-pin, SOIC plastic package shown in the pinout diagram in [Figure 3-1](#). [Figure 3-2](#) shows the device with the package cap decapped to reveal the die for heavy ion testing. [Figure 3-3](#) shows the evaluation board used for radiation testing. [Figure 3-4](#) shows the bias diagram used for Single-Event Latch-up (SEL) testing. [Figure 3-5](#) and [Figure 3-4](#) show the bias diagrams used for Single-Event Transient (SET) testing.



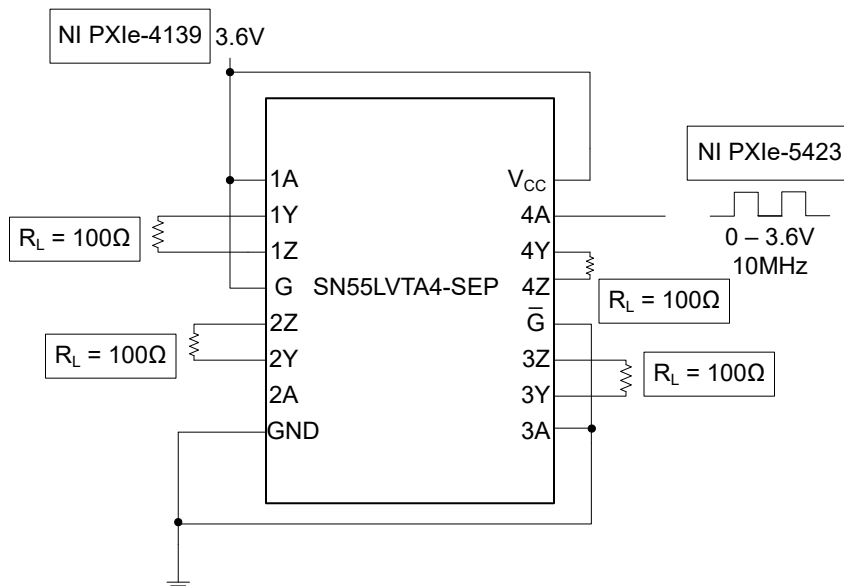
**Figure 3-1. SN55LVTA4-SEP Pinout Diagram**



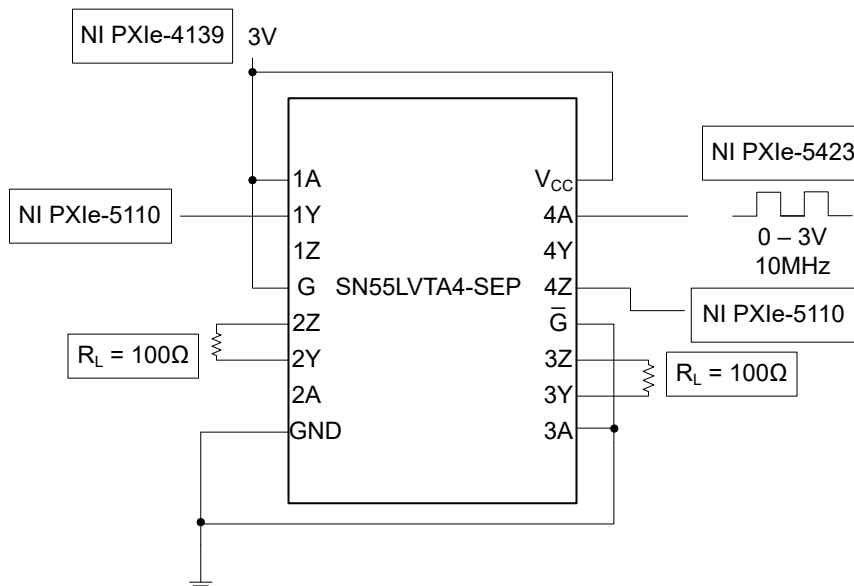
**Figure 3-2. Photo of SN55LVTA4-SEP Package Decapped**



**Figure 3-3. SN55LVTA4-SEP Evaluation Board (Top View)**



**Figure 3-4. SN55LVTA4-SEP SEL Bias Diagram**



**Figure 3-5. SN55LVTA4-SEP SET Bias Diagram**

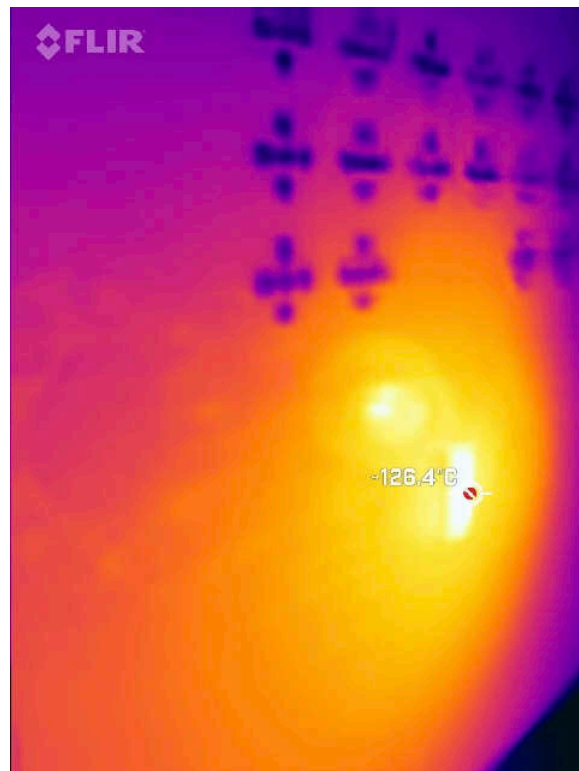
## 4 Irradiation Facility and Setup

The heavy ion species used for the SEE studies on this product were provided and delivered by the Facility for Rare Isotope Beams (FRIB) at Michigan State University (FRIB Single Event Effects (FSEE) Facility's linear accelerator.) The FSEE Facility has a dedicated beamline built on the FRIB linac infrastructure with a user experimental station at the end of the FSEE beamline. Ion beams are delivered with high uniformity over a 1-inch diameter exposure area using a thin vacuum window. For this study, ion flux of  $1 \times 10^5$  ions /  $\text{cm}^2\text{-s}$  was used to provide heavy ion fluence of  $1 \times 10^7$  ions /  $\text{cm}^2$  using  $^{129}\text{Xe}$  ion at a linac energy of 25 MeV /  $\mu$ . Ion beam uniformity for all tests was 97.5%.

Figure 4-1 shows one of the three SN55LVTA4-SEP test boards used for experiments at the MSU facility. The in-air gap between the device and the ion beam port window was maintained at 70mm for all runs.



**Figure 4-1. SN55LVTA4-SEP Evaluation Board at the MSU Facility**



**Figure 4-2. SN55LVTA4-SEP Thermal Image for SEL**

## 5 Results

### 5.1 Single-Event Latch-up (SEL) Results

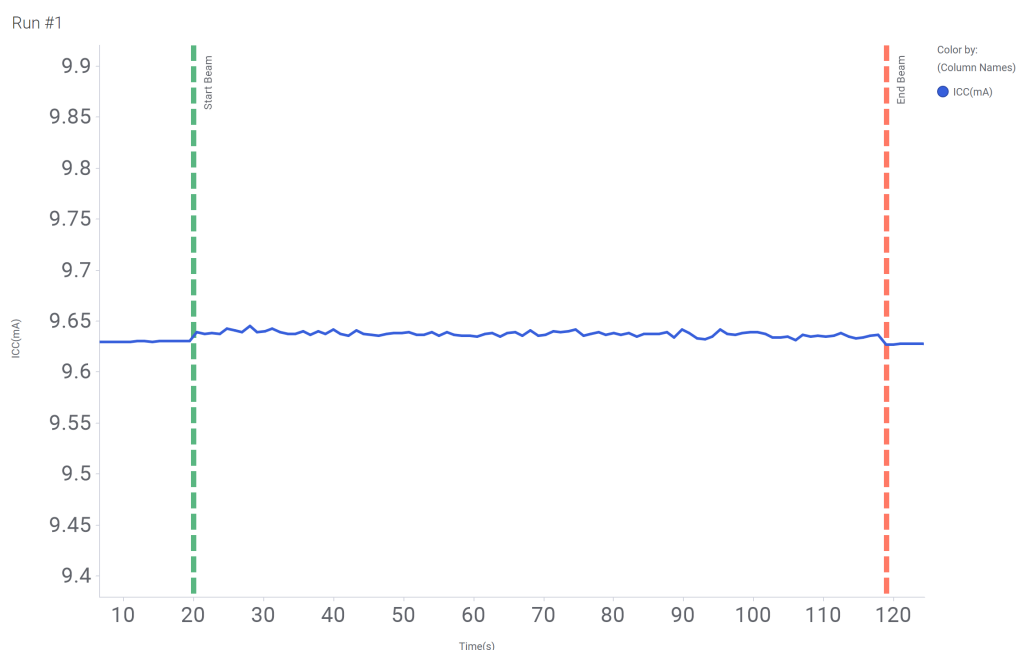
During SEL characterization, the device was heated using forced hot air, maintaining device temperature at 125°C. A FLIR (FLIR ONE Pro LT) thermal camera was used to validate die temperature to make sure the device was accurately heated (see [Figure 4-2](#).) The species used for SEL testing was a Xenon ( $^{129}\text{Xe}$ ) ion at 25MeV /  $\mu$  with an angle-of-incidence of 0° for an LET<sub>EFF</sub> of 50MeV-cm<sup>2</sup>/mg. A fluence of approximately  $1 \times 10^7$  ions / cm<sup>2</sup> was used for each run.

The three devices were powered up and exposed to the heavy-ions using the maximum recommended supply voltage of 3.6V using a National Instruments™ PXI Chassis PXIe-4139 on VCC and input 1A and a 3.6V, 10MHz square wave on input 4A using a National Instruments™ PXI Chassis PXIe-5423 function generator. The run duration to achieve this fluence was approximately 100 seconds. As listed in [Table 5-1](#), no SEL events were observed during the eight runs, indicating that the SN55LVTA4-SEP is SEL-free. [Figure 5-1](#), [Figure 5-2](#), and [Figure 5-3](#) show the plots of current versus time for runs one, three, and six, respectively.

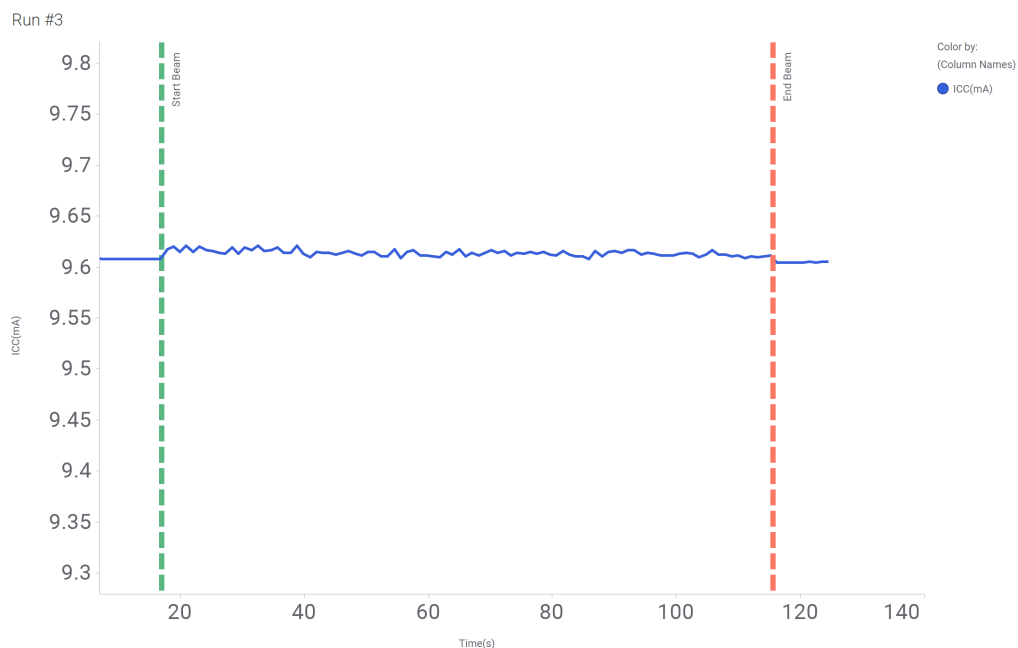
A single unit was tested with a fluence of 1.5E+07 using the same bias condition as above. No SEL events occurred on these runs either.

**Table 5-1. Summary of SN55LVTA4-SEP SEL Test Conditions and Results**

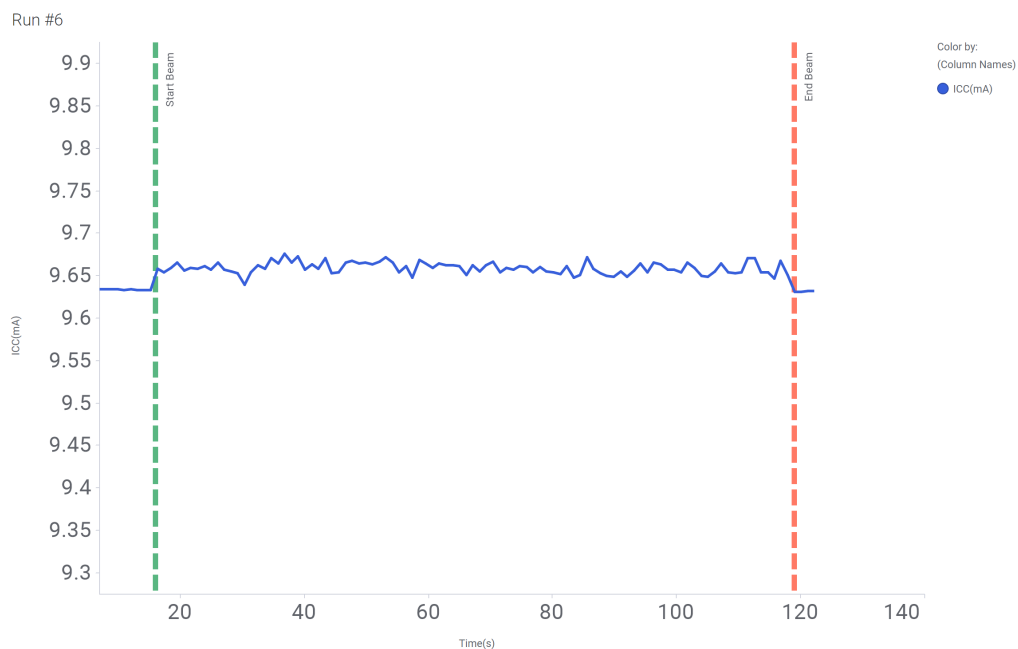
Run Number	Unit Number	Distance (mm)	Temperature (°C)	Ion	Angle	Flux (ions × cm <sup>2</sup> / mg)	Fluence (Number of ions)	LET <sub>EFF</sub> (MeV × cm <sup>2</sup> /mg)	Did an SEL Event Occur?
1	1	70	125	Xe	0°	1.00E+05	1.00E+07	50	No
2	1	70	125	Xe	0°	1.00E+05	1.00E+07	50	No
3	2	70	125	Xe	0°	1.00E+05	1.00E+07	50	No
4	2	70	125	Xe	0°	1.00E+05	1.00E+07	50	No
5	3	70	125	Xe	0°	1.00E+05	1.00E+07	50	No
6	3	70	125	Xe	0°	1.00E+05	1.00E+07	50	No
7	4	70	125	Xe	0°	1.00E+05	1.50E+07	50	No
8	4	70	125	Xe	0°	1.00E+05	1.50E+07	50	No



**Figure 5-1. Current Versus Time for Run 1 of the SN55LVTA4-SEP at T = 125°C**



**Figure 5-2. Current Versus Time for Run 3 of the SN55LVTA4-SEP at T = 125°C**



**Figure 5-3. Current Versus Time for Run 6 of the SN55LVTA4-SEP at T = 125°C**

No SEL events were observed, indicating that the SN55LVTA4-SEP is SEL-immune at  $LET_{EFF} = 50 \text{ MeV} \cdot \text{cm}^2 / \text{mg}$  and  $T = 125^\circ\text{C}$ . Using the MFTF method shown in [Single-Event Effects \(SEE\) Confidence Internal Calculations](#), the upper-bound cross-section (using a 95% confidence level) is calculated as:

$$\sigma_{SEL} \leq 6.15 \times 10^{-8} \text{ cm}^2 / \text{device for } LET_{EFF} = 50 \text{ MeV} \cdot \text{cm}^2 / \text{mg and } T = 125^\circ\text{C} \quad (1)$$

## 5.2 Single-Event Transients (SET) Results

SETs are defined as heavy-ion-induced transient upsets on output pins 1Y and 4Z of the SN55LVTA4-SEP. SET testing was performed at room temperature (no external temperature control applied). The species used for the SET testing was  $^{129}\text{Xe}$  for a  $\text{LET}_{\text{EFF}} = 50 \text{ MeV} \times \text{cm}^2 / \text{mg}$ . Flux of approximately  $10^5 \text{ ions} / \text{cm}^2 \times \text{s}$  and a fluence of approximately  $10^7 \text{ ions} / \text{cm}^2$  were used for the SET runs.

Three units were tested across multiple input conditions to determine the worst-case setup for SETs. The unit was tested with  $V_{\text{CC}}$  of 3V. All combinations of VCC and scope trigger configurations showed no transient upsets, as listed in [Table 5-2](#)

To capture SETs, one NI PXI-5110 scope card was used to continuously monitor the output voltage on pin 4Z, and one PXI-5172 scope card was used to continuously monitor the output voltage on pin 1Y. The scope monitoring the square wave output signal was configured to a rising edge window trigger of  $\pm 5\%$  and  $\pm 20\%$ , while the scope monitoring the static output signal was configured to a rising edge voltage trigger of  $\pm 5\%$  and  $\pm 20\%$  respectively. The NI scopes were programmed to a sample rate of 100M samples per second (S/s) and recorded 1000 samples, with a 20% pretrigger reference, in case of an event (trigger). The setup was verified for each run to ensure no false triggers was captured before the beam was turned on. The  $\pm 5\%$  threshold on the static and square wave outputs was determined to be the lowest threshold capable of not providing false triggers due to noise.

Under heavy-ions, the SN55LVTA4-SEP did not exhibit any transient upsets.

**Table 5-2. Summary of SN55LVTA4-SEP SET Test Condition and Results**

Run Number	Unit Number	Voltage Level	Ion	$\text{LET}_{\text{EFF}}$ (MeV $\times$ $\text{cm}^2/\text{mg}$ )	FLUX (ions $\times$ $\text{cm}^2/\text{mg}$ )	Fluence (Number ions)	Voltage Trigger	Window Trigger	SET Upsets
9	5	3V	Xe	50	1.00E+05	1.00E+07	20%	20%	0
10	5	3V	Xe	50	1.00E+05	1.00E+07	5%	5%	0

Using the MFTF method shown in [Single-Event Effects \(SEE\) Confidence Internal Calculations](#), the upper-bound cross-section (using a 95% confidence level) is calculated as:

$$\sigma_{\text{SET}} \leq 1.84 \times 10^{-7} \text{ cm}^2 / \text{device for } \text{LET}_{\text{EFF}} = 50 \text{ MeV} \cdot \text{cm}^2 / \text{mg and } T = 25^\circ\text{C} \quad (2)$$

## 6 Summary

The purpose of this study was to characterize the effects of heavy-ion irradiation on the single-event latch-up (SEL) performance of the SN55LVTA4-SEP radiation-tolerant, quad channel differential line driver. SEE performance was verified at minimum (3V) and maximum (3.6V) operating conditions. Heavy-ions with an  $LET_{EFF}$  of 50MeV-cm<sup>2</sup>/mg were used to irradiate five production devices with a fluence of  $1 \times 10^7$  ions / cm<sup>2</sup>. The results demonstrate that the SN55LVTA4-SEP is SEL-free up to  $LET_{EFF} = 50\text{MeV-cm}^2/\text{mg}$  as 125°C. SET performance for the minimum and maximum operating voltage saw no excursions  $\geq |5\%|$ , as shown and discussed in this report.

## 7 References

1. M. Shoga and D. Binder, "Theory of Single Event Latchup in Complementary Metal-Oxide Semiconductor Integrated Circuits", *IEEE Trans. Nucl. Sci.*, Vol. 33(6), Dec. 1986, pp. 1714-1717.
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8. A. J. Tylka, W. F. Dietrich, and P. R. Boberg, "Probability distributions of high-energy solar-heavy-ion fluxes from IMP-8: 1973-1996", *IEEE Trans. on Nucl. Sci.*, Vol. 44(6), Dec. 1997, pp. 2140-2149.

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